

SEMI-CONDUCTIVE CERAMIC DISC CAPACITOR (Surface Layer Type)

POE-D09-00-E-08

Ver: 8

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PRODUCT SPECIFICATION

PRODUCT: CERAMIC DISC CAPACITOR

TYPE: CERAMIC DISC CAPACITOR (Surface Layer Type)

CUSTOMER:

DOC. NO.: POE-D09-00-E-08

Ver.: 8

APPROVED BY CUSTOMER

VENDOR:

☐ WALSIN TECHNOLOGY CORPORATION

566-1, KAO SHI ROAD, YANG-MEI

TAO-YUAN, TAIWAN

 $\hfill \square$ PAN OVERSEAS (GUANGZHOU) ELECTRONIC CO.,LTD.

NO.277,HONG MING ROAD,EASTERN SECTION, GUANG ZHOU ECONOMIC AND TECHNOLOGY

DEVELOPMENT ZONE, CHINA

MAKER: PAN OVERSEAS (GUANGZHOU) ELECTRONIC CO.,LTD.

NO.277,HONG MING ROAD,EASTERN SECTION, GUANG ZHOU ECONOMIC AND TECHNOLOGY DEVELOPMENT ZONE,CHINA







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Record of change

Date	Date Version Description					
2008.6.3	1	1. D16-00-E-09(before) → POE-D09-00-E-01(1 st edition)				
2008.8.22	2	1. Complete lead code Add last SAP code "H" for halogen and Pb free, epoxy resin.				
2008.12.12	3	1.Complete the 13 th to 17 th codes of SAP P/N. 2.Page layout adjustment.	4-6			
2009.8.21	4	1. Change PSA & POE logo to Walsin & POE logo.				
2011/3/8	5	Review the capacitance range, delete the part of 223/333/473/683.				
2013/5/8	6	 Review the Lead diameter φ from 0.60 +/-0.06mm to 0.55+/-0.05mm Review the "shall be omitted when DΦ<6.0 mm & shall be omitted 	6,8			
		when D Φ <8.0 mm." to "shall be omitted when D Φ <060 &shall be omitted when D Φ <080 . "	7			
		3. Review the Solderability temperature from $255(+5/-0)^{\circ}$ C to 245 ± 5 °C., Solderability time from 2 ± 0.5 s to 5 ± 0.5 s,	10			
2016/3/3	7	Review the Available lead code of Lead Configuration.	5			
		2. Delete the definition about "Old Part No."	5-6			
		3. Review the Specification and test method.	10-12			
2017/10/31	8	1. Review the Available lead code of Lead Configuration.	5			



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1. Part number for SAP system(total eighteen code):

• Temperature characteristic:

Code	FY(Y5V)		
Operating temperature	-25°C to +85°C		
Cap. change	-82%~+22%		

2 Rated voltage (Vdc):

Voltage	16V	25V	50V			
Code	160	250	500			

3Capacitance(pF):

Capacitors (pF)	100000	
Code	104	

♦ Capacitance tolerance : Z=+80%-20%

6 Nominal body diameter dimension (Ref. to page. 7 Dφ Code spec.).

6 Code of lead type: Please refer to Item "2.Mechanical".

Packing mode and lead's length (identified by 2-figure code)

Taping Code	Description
AN	Ammo / Pitch of component:12.7 mm

Bulk Code	Description PASSIVE
3E	Lead's length L: 3.5mm
04	Lead's length L: 4mm
4E	Lead's length L: 4.5mm
20	Lead's length L; 20mm

8Length tolerance

Code	Description
A	± 0.5 mm(Only for short kink lead code "D / X / H")
В	±1.0 mm
С	Min.
D	Taping special purpose

9Pitch

Code	Description
5	5.0±0.8mm (For Bulk)
5	5.0+0.8mm-0.2mm (For Taping)

Coating code

Code	Description		
P	Phenolic resin -Pb free, voltage ≤ 1kV		
A	Halogen free and Pb free, phenolic resin, voltage ≤ 1kV		



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2. Mechanical:

Available lead code (Phenolic resin coating): (unit: mm)

Lead type	SAP P/N (13-17) digits	Pitch (F)	Lead length (L)	Packing	Lead configuration
Lead style: B	B20C5	5.0 ± 0.8	20 MIN.	Bulk	D max.
Straight long lead	BAND5	5.0 +0.8 -0.2	Taping Spec. (Ref.to page.8)	Tap. Ammo	e The F
	L4EB5	5.0 ± 0.8	4.5 ± 1.0		D max.
Lead style : L Straight short lead	L05B5	5.0 ± 0.8	5.0 ± 1.0	Bulk	*
	L05B0	10 ± 1.0	5.0 ± 1.0		Ø d- L
	H3EA5	5.0 ± 0.8	$+3.5 \pm 0.5$		D max. T max.
	H04A5	5.0 ± 0.8	4.0 ± 0.5		
Lead style: H	H4EB5	5.0 ± 0.8	4.5 ± 1.0	Bulk	
Inside kink	H05B5	5.0 ± 0.8	5.0 ±1.0	(F1) E	× I
lead	H20C5	5.0 ± 0.8	20 MIN.	$ ightharpoonup_{S_G}$	S T F S T S T S T S T S T S T S T S T S
	HAND5	5.0 +0.8 -0.2	Taping SPEC. (Ref.to page.8)	Tap. Ammo	
	X3EA5	5.0±0.8 PASS	IVE SYSTEM ALLIANG 3.5 ± 0.5	ion (GM)	D max.
Lead style: X Outside kink lead	X04A5	5.0±0.8	4.0 ± 0.5	Bulk	O max
	X05B5 5.0±0.8/		nnos.0±1.0	William	5 T F Ø d L

% Lead diameter ϕ = 0.55 +/-0.05mm

※ e (Coating **extension** on leads):

For straight lead style: 1.5mmMax;

For kink lead style: not exceed the kink.

%When Dφ≥11mm, only for bulk, but Dφ≤10mm can do Bulk or Taping.



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3. Capacitance value vs. rated voltage, product diameter:

Manufacturing capacity list								
T.C.	T.C. FY (Y5V) CLASS III							
Rate voltage	16	16V 25V 50V						
Dφ	050	060	050	060	050	060		
D max. (mm)	6.0	7.0	6.0	7.0	6.0	7.0		
T max. (mm)	3.5	3.5	3.5	3.5	3.5	3.5		
100000		104		104		104		

4. Marking:

T. Man King.					
Marking	(1) (3) (3) (4)				
Temp. char.	Y5V: Shall be omitted				
(1). Rated capacitance	Identified by 3-Figure Code. Ex. 100000pF→"104",				
(2). Capacitance tolerance	Z=+80%-20%				
(2) P 4 1 14	16V&25V Marked with code: 16V→"16V", 25V→"25V"				
(3). Rated voltage	50V Shall be marked "_" under the rated capacitance.				
(4). Manufacturer's identification	50V: Shall be marked as """, but shall be omitted when DΦ<060. 16V&25V: Shall be marked as "", but shall be omitted when DΦ<080.				
1 1					



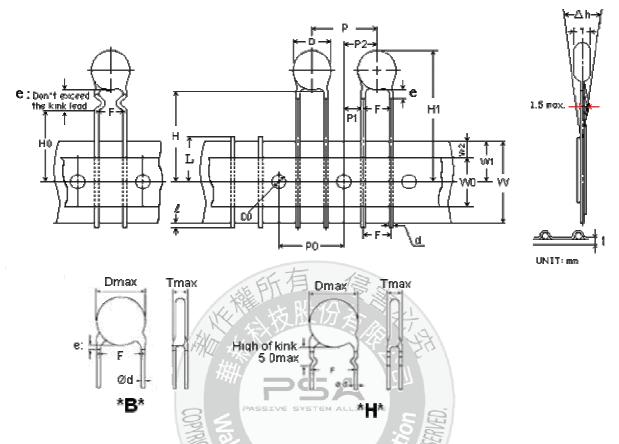
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5. Taping specifications:

* Lead spacing: $F=5.0^{+0.8}_{-0.2}$ (mm)

• 12.7mm pitch/lead spacing 5.0mm taping

Lead code: *BAND5 & *DAND5 & *HAND5



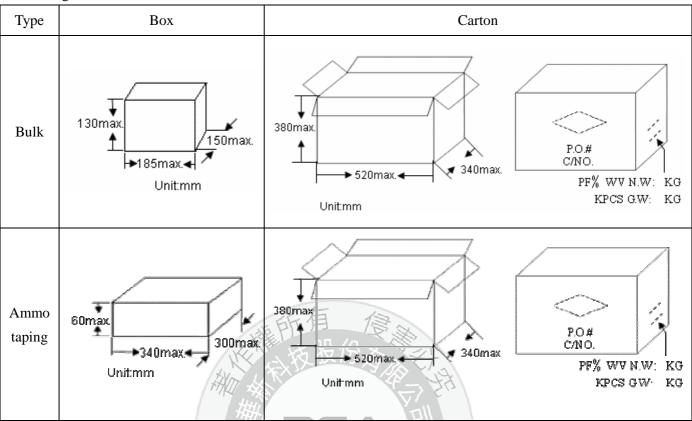
Item			Specification		Remarks	
			Value	Tolerance	Kemarks	
Body diameter	75/1/2	D	02*	max.	See Section"3. Capacitance value vs. rated	
Body thickness	\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\	χ_{L} T	*	max.	voltage, product diameter".	
Lead-wire diameter		///_d/ /-\	0.55	±0.05		
Pitch of component		P	12.7	±1.0		
Feed hole pitch		P0	12.7	±0.3	Cumulative pitch erroe:1.0mm/20 pitch	
Feed hole center to lead		P1	3.85	±0.7	To be measured at bottom of clinch	
Hole center to component center		P2	6.35	±1.3		
Lead-to-lead distance		F	5.0	+0.8,-0.2		
Component alignment, F-R		∆h	0	±2.0		
Tape width		W	18.0	+1.0,-0.5		
Hole-down tape width		W0	11.0	min.		
Hole position		W1	9.0	+0.75,-0.5		
Hole-down tape position		W2	3.0	max.		
Height of component form tape	For straight lead type	Н	20.0	+1.0 -0.5		
center	For kinked lead type	H0	16.0	±0.5		
Component height		H1	32.25	max.		
Lead-wire protrusion		()	2.0	max.	Or the end of lead wire may be inside the tape.	
Food hole diameter		D0	4.0	±0.2		
Total tape thickness		t	0.7	±0.2	Ground paper:0.5±0.1mm	
Length of sniped lead		L	11.0	max.		
Coating rundown on leads		e	Please refer to page 6 "e(Coating extension on leads)".			



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6. Packing Baggage:

6.1 Packing size:



6.2. Pakaging Styles

Bulk: 1000pcs/bag
Taping: 2000pcs/box for Ammo



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7. Specification and test method:

7.1 SCOPE: THIS SPECIFICATION APPLIES TO SEMI-CONDUCTIVE CERAMIC TYPE CAPACITOR.

7.2 TEST CONDITIONS:

UNLESS OTHERWISE SPECIFIED, ALL TESTS SHALL BE OPERATED AT THE STANDARD TEST CONDITIONS OF TEMPERATURE 5° C TO 35° C AND RELATIVE HUMIDITY 45% TO 85%. WHEN FAILS A TEST, RETEST BE OPERATED AT THE CONDITIONS OF TEMPERATURE 25° C $\pm 2^{\circ}$ C, RELATIVE HUMIDITY OF 60% TO 70% AND BAROMETRIC PRESSURE 860 TO 1060 MBAR..

7.3 HANDLE PROCEDURE:

TO AVOID UNEXPECTED TESTING RESULTS FROM OCCURRING, THE TESTED CAPACITOR MUST BE KEPT AT ROOM TEMPERATURE FOR AT LEAST 30 MINUTES AND COMPLETELY DISCHARGED.

7.4 TEST ITEMS:

ITEM	POST-TEST REQUIREMENTS	TESTING PROCEDURE		
APPEARANCE STRUCTURE SIZE	NO ABNORMALITIES	AS STATED IN SECTION 3.		
MARKING		AS STATED IN SECTION 4		
WITHSTAND VOLTAGE	NO ABNORMALITIES	200% RATED VOLTAGE WITH 10mA MAX. CHARGING CURRENT FOR $1\sim5$ SEC.		
INSULATION RESISTANCE	RATED VOLTAGE; $12\sim16\text{VDC}$ LESSER OF $100\text{M}\Omega$ OR $10\text{ M}\Omega \cdot \mu\text{F}$ RATED VOLTAGE: $25\sim50\text{VDC}$ LESSER OF $1000\text{M}\Omega$ OR $20\text{ M}\Omega \cdot \mu\text{F}$	INSULATION RESISTANCE SHALL BE MEASURED AT 60±5 SECONDS , 10±1 VDC		
CAPACITANCE	TOLERANCE : M : ±20% Z : +80-20%	TESTING FREQUENCY : 1 KHZ \pm 20 % TESTING VOLTAGE : 0.1 VRMS MAX.		
TEMPERATURE RANGE	Y5V : -25°C ~+85°€	no se		
DISSIPATION FACTOR (D.F.)	12~16VDC : BELOW 7.5% 25~50VDC : BELOW 5.0%	AS ABOVE STIPULATION OF CAPACITANCE		
_	CAP. CHANGE : Y5V : WITHIN +22% ~-82%	CAPACITANCE SHALL BE MEASURED AT 25°C. AND CLASSIFIED AS CAP. CHANGE: -25°C ~85°C Pre-treatment: Capacitor shall be stored at125±3°C for 1hour.then placed at **1room condition for 24±2hours		
TERMINAL STRENGTH	TENSILE STRENGTH : NO BREAKDOWN	WIRE DIA.0.5 M/M, LOADING WEIGHT 0.5KGS FOR 10±1 SECONDS WIRE DIA.0.6 M/M, LOADING WEIGHT 1.0KGS FOR 10±1 SECONDS		
	BENDING STRENGTH : NO BREAKDOWN	WIRE DIA.0.5 M/M, LOADING WEIGHT 0.25 KGS WIRE DIA.0.6 M/M, LOADING WEIGHT 0.5 KGS (BENDING BACK AND FORTH 90 DEGREE TWICE)		
SOLDERBILITY	LEAD WIRE SHALL BE SOLDERED OVER 3/4 OF THE	TO COMPLY WITH JIS-C-5102 8.4 SOLDER TEMPERATURE245±5°C AND DIPPING TIME 5±0.5 SECONDS. FLUX: WEIGHT RATIO OF RESIN 25%.		
	CIRCUMFERENTIAL DIRECTION.	LOA. WEIGHT KATTO OF RESHV 2570.		

^{** 1&}quot;room condition" Temperature:15~35, Relative humidity: 45~75%, Atmospheric pressure:86~106kPa



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ITEM	POST-TEST REQUIREMENTS	TESTING PROCEDURE
	APPEARANCE :	LEAD WIRE OR TERMINALS SHALL BE IMMERSED
	NO ABNORMALITIES	UP TO 2.0 M/M FORM BODY. (A) BODY DIA. ≤ 5.0mm: INTO THE MOLTEN SOLDER OF WHICH TEMPERATURE: 260(+5/-0)°C FOR
	CAP. CHANGE :	3.0±0.5 SECONDS.
SOLDERING	Y5V: ± 30%	(B) BODY DIA. > 5.0mm: INTO THE MOLTEN SOLDER OF WHICH TEMPERATURE 260(+5/-0)°C FOR
HEAT	Y5R: WITHIN ± 15%	5~10 SECONDS. THEN LEAVE AT STANDARD TEST CONDITIONS FOR
RESISTANCE		1~2 HOURS, THEN MEASURED.
	WITHSTAND VOLTAGE :	*WHEN SOLDERING CAPACITOR WITH A
	(BETWEEN TERMINALS)	SOLDERING IRON, IT SHOULD BE PERFORMED IN FOLLOWING CONDITIONS.
		TEMPERATURE OF IRON-TIP: 350~400 °C
	NO ABNORMALITIES	SOLDERING IRON WATTAGE : 50W MAX.
		SOLDERING TIME : 3.5 SEC. MAX.
	APPEARANCE :	CAPACITORS SHALL BE SUBJECTED TO A RELATIVE
	NO ABNORMALITIES	
	CAP. CHANGE:	HUMIDITY OF 90 \sim 95% AT 40±2°C FOR 500(+24/-0)
	Y5V: ±30%	HOURS.
HUMIDITY	Y5R: WITHIN ± 15%	THEN DRIED FOR24±2 HOURS AND MEASURED.
CHARACTERISTIC	D.F.: 12~16VDC / 10 % MAX.	
(STABLE	25~50VDC: 7.5% MAX.	
,	INSULATION RESISTANCE:	5A 🔛
SITUATION)	$12\sim16$ VDC: LESSER OF 50 MΩ SYST	EM ALLIANCE
	OR 5 MΩ · μF	
	25~50VDC: LESSER OF 500MΩ	
	OR 20 MΩ · MF	
	APPEARANCE : NO ABNORMALITIES	CAPACITORS SHALL BE SUBJECTED TO A RELATIVE
		HUMIDITY OF 90 \sim 95 % AT 40 ± 2°C FOR 500(+24/-0)
	Y5V: ±30%	HOURS WITH RATED VOLTAGE APPLIED WITH 10MA
HUMIDITY	Y5R: WITHIN ± 15%	
LOADING	D.F.: 12~16VDC: 10 % MAX. 25~50VDC: 7.5% MAX.	MAX.
	INSULATION RESISTANCE :	THEN DRIED FOR 24±2 HOURS AND MEASURED.
	$12\sim$ 16VDC: LESSER OF 50 MΩ	Pre-treatment:
	OR 5 M $\Omega \cdot \mu F$ 25~50VDC : LESSER OF 500M Ω	Capacitor shall be stored at125±3°C for 1hour.then placed at **
	OR 20 MΩ · μF	1room condition for 24±2hours

^{*\}times 1"room condition" Temperature: 15~35, Relative humidity: 45~75\times, Atmospheric pressure: 86~106kPa



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ITEM	POST-TEST REQUIREMENTS	TESTING PROCEDURE		
	APPEARANCE :	CAPACITORS SHALL BE SUBJECTED TO A TEST OF		
	NO ABNORMALITIES	150% RATED VOLTAGE WITH 10MA MAX. FOR HIGH		
	CAP. CHANGE :	$1000(+48/-0)$ HOURS AT $85\pm2^{\circ}$ C AND THEN DRIED FOR		
	Y5V: ±30%	24±2 HOURS AND MEASURED		
	Y5R: WITHIN ± 15%			
HIGH	D.F.: 12~16VDC: 10 % MAX.	Pre-treatment:		
TEMPERATURE	25~50VDC: 7.5% MAX.	Capacitor shall be stored at125±3°C for 1hour.then placed a		
LOADING	INSULATION RESISTANCE :			
	$12\sim16$ VDC: LESSER OF 50 M Ω	13		
	OR 5 M Ω \cdot μ F	(A) X 图 (A)		
	25~50VDC: LESSER OF 500MΩ	10000000000000000000000000000000000000		
	OR 20 MΩ · μF			
	APPEARANCE:	CAPACITORS SHALL BE SUBJECTED		
	NO ABNORMALITIES	TO: 5		
	CAP. CHANGE	$-25\pm3^{\circ} C (30\pm3 min) \rightarrow 25^{\circ} C (3 min) \rightarrow 85\pm3^{\circ} C (30\pm3 min)$ $\rightarrow 25^{\circ} C (3 min) FOR 5 CYCLE.$		
	Y5V: ±30% MAX	25 COMMIN FOR 5 CTCLL.		
	Y5R: ±15% MAX	Pre-treatment: Capacitor shall be stored at125±3°C for 1hour.then placed at **\text{1}\text{room condition for 24±2hours}		
	D.F.			
TEMPERATURE	≤16VDC: 10% MAX			
CYCLING	25VDC~50VDC: 7.5%MAX			
	INSULATION RESISTANCE :			
	INSULATION RESISTANCE:			
	\leq 16VDC: LESSER OF 50 M Ω			
	OR 5 MΩ*uF			
	25VDC~50VDC:			
	LESSER OF 50 M Ω			
	OR 5 MΩ*uF			

^{* 1&}quot;room condition" Temperature:15~35, Relative humidity: 45~75%, Atmospheric pressure:86~106kPa



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8. Cautions & notices:

8.1. Caution (Rating)

I. Operating Voltage

When DC-rated capacitors are to be used in AC or ripple current circuits, be sure to maintain the Vp-p value of the applied voltage or the Vo-p which contains DC bias within the rated voltage range.

When the voltage is applied to the circuit, starting or stopping may generate irregular voltage for a transit period because of resonance or switching. Be sure to use a capacitor with a rated voltage range that includes these irregular voltages.

Voltage	DC Voltage	DC+AC Voltage	AC Voltage	Pulse Voltage (1)	Pulse Voltage (2)
Positional measurement	Vo-p	Vo-p	Vp-p	Vp-p	Vp-p

II. Operating Temperature and Self-generated Heat

Keep the surface temperature of a capacitor below the upper limit of its rated operating temperature range. Be sure to take into account the heat generated by the capacitor itself. When the capacitor is used in a high frequency current, pulse current or similar current, it may self-generate heat due to dielectric loss. The frequency of the applied sine wave voltage should be less than 10kHz. The applied voltage load (*) should be such that the capacitor's self-generated heat is within 20°C at an atmosphere temperature of 25°C. When measuring, use a thermocouple of small thermal capacity-K of Ø0.1mm in conditions where the capacitor is not affected by radiant heat from other components or surrounding ambient fluctuations.

Excessive heat may lead to deterioration of the capacitor's characteristics and reliability. (Never attempt to perform measurement with the cooling fan running. Otherwise, accurate measurement cannot be ensured.)

III. Fail-Safe

When capacitor is broken, failure may result in a short circuit. Be sure to provide an appropriate fail-safe function like a fuse on your product if failure would follow an electric shock, fire or fume.

8.2. Caution (Storage and operating condition)

I. Operating and storage environment

The insulating coating of capacitors does not form a perfect seal; therefore, do not use or store capacitors in a corrosive atmosphere, especially where chloride gas, sulfide gas, acid, alkali, salt or the like are present. And avoid exposure to moisture. Before cleaning, bonding or molding this product, verify that these processes do not affect product quality by testing the performance of a cleaned, bonded or molded product in the intended equipment. Store the capacitors where the temperature and relative humidity do not exceed –10 to 40 degrees centigrade and 15 to 85 % for 6 months maximum and use within the period after receiving the capacitors.

FAILURE TO FOLLOW THE ABOVE CAUTIONS MAY RESULT, WORST CASE, IN A SHORT CIRCUIT AND CAUSE FUMING OR PARTIAL DISPERSION WHEN THE PRODUCT IS USED.



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8.3. Caution (Soldering and Mounting)

I. Vibration and impact

Do not expose a capacitor or its leads to excessive shock or vibration during use.

II. Soldering

When soldering this product to a PCB/PWB, do not exceed the solder heat resistance specification of the capacitor. Subjecting this product to excessive heating could melt the internal junction solder and may result in thermal shocks that can crack the ceramic element. When soldering capacitor with a soldering iron, it should be performed in following conditions.

Temperature of iron-tip: 400 degrees C. max.

Soldering iron wattage: 50W max.

Soldering time: 3.5 sec. max.

FAILURE TO FOLLOW THE ABOVE CAUTIONS MAY RESULT, WORST CASE, IN A SHORT CIRCUIT AND CAUSE FUMING OR PARTIAL DISPERSION WHEN THE PRODUCT IS USED.

8.4. Caution (Handling)

Vibration and impact

Do not expose a capacitor or its leads to excessive shock or vibration during use.

FAILURE TO FOLLOW THE ABOVE CAUTIONS MAY RESULT, WORST CASE, IN A SHORT CIRCUIT AND CAUSE FUMING OR PARTIAL DISPERSION WHEN THE PROUCT IS USED.

8.5. Notice

PASSIVE SYSTEM ALLIANCE

8.5.1. Notice (Soldering and Mounting)

Cleaning (ultrasonic cleaning)

To perform ultrasonic cleaning, observe the following conditions.

Rinse bath capacity: Output of 20 watts per liter or less.

Rinsing time: 5 min. maximum.

Do not vibrate the PCB/PWB directly.

Excessive ultrasonic cleaning may lead to fatigue destruction of the lead wires.

8.5.2. Notice (Rating)

Capacitance change of capacitor

Class 3 series:

Capacitors have an aging characteristic, whereby the capacitor continually decreases its capacitance slightly if the capacitor is left on for a long time. Moreover, capacitance might change greatly depending on the surrounding temperature or an applied voltage. So, it is not likely to be suitable for use in a time constant circuit.

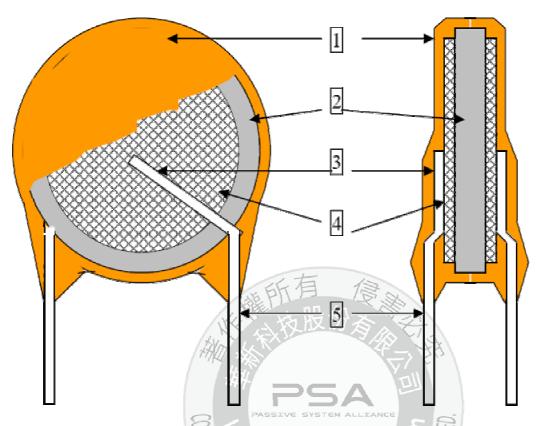
Please contact us if you need detailed information.



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9. Drawing of internal structure and material list:

產品結構圖



NO.	部位	材質	構成部份	供應商
	Part name	Material	Component	Vendor
1	Insulation Coating	Phenolinsulating varnish	Phenolpolymer, Filler, Pigment	Namics
		- WOLU	GY COKPORA	Hua Xing
2	Dielectric Element	Ceramic	BaTiO3	Wang Feng
				Fenghua
3	Solder	Tin-silver	Sn97.5-Ag2.5	Huajun
3	Solder	Till-Silvei	51197.5-Ag2.5	Haili
4	Electrodes	Λα	Silver,Glass frit	Daejoo
4	Electiodes	Ag	Silvei, Glass IIII	Xinguang
		Tinned conner	Substrate metal:Fe&Cu	Hengtai
5 Le	Leads wire	Tinned copper clad steel wire	Surface plating:Sn 100%	Wuhu
		ciau steel wire		Taililai